



PRODUCT DATA SHEET

PETLIN LD C150Y
Low Density Polyethylene

PETLIN LD C150Y is a low density polyethylene resin for general purpose and thin film applications. It is produced by the state-of-the-art DSM Stamicarbon tubular process. It contains antioxidant (BHT free), slip and antiblock additives. It is intended primarily for blown film process.

- Characteristics** : low gels, high drawdown, high clarity, high gloss, good sealability, high slip, high antiblocking.
- Applications** : thin gauge film for : textile, laundry, dry cleaning, garment ; crosslinked foams ; zip bags.
- Recommended gauges** : 15 - 60 microns
- Extrusion Conditions** : for blown film : melt temperature 145-165°C , recommended blow-up-ratio of 2 to 3 : 1
- Typical Data** : (25 microns film)

Properties	Units	Typical values	Test methods	
<u>Polymer properties :</u>				
Melt Flow Rate:	dg/min	5	ISO 1133	
Density	kg/m ³	921	ISO 1183 (A)	
<u>Optical properties :</u>				
Gloss (45°)	%	66	ASTM D2457	
Haze	%	6.5	ASTM D1003A	
<u>Mechanical properties :</u>				
Impact strength	g	86	ASTM D1709	
Tear strength	TD	kN/m	30	ISO 6383-2
	MD	kN/m	80	
Tensile stress at break	TD	N/mm ²	15	ISO R527-3
	MD	N/mm ²	26	
Strain at break	TD	%	610	ISO R527-3
	MD	%	149	
Modulus of elasticity	TD	N/mm ²	224	ISO R527-3
	MD	N/mm ²	202	
Coefficient of friction	-	0.1	ASTM D1894	

The properties shown above are typical values and are not to be taken as specifications.

Food contact approval status :

This material complies with FDA 21 CFR 177.1520 when used unmodified and according to good manufacturing practices for food contact applications. Accordingly, this material may be used in all food contact applications.

IMPORTANT NOTICE :

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